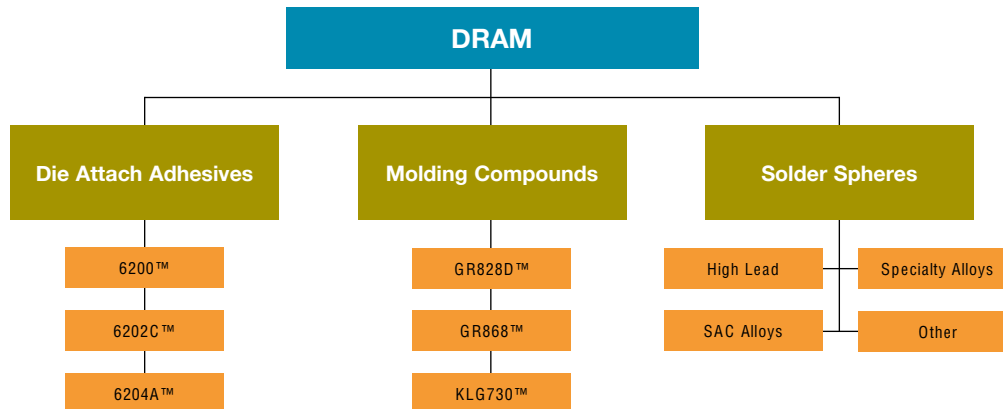


# SEMICONDUCTOR MARKET SOLUTIONS

## DRAM



### DIE ATTACH ADHESIVES

PRODUCT	DESCRIPTION	MRT	ELECTRICAL CONDUCTIVITY	DISPENSABILITY	CURE SCHEDULE	THERMAL CONDUCTIVITY, W/mK
6200™	B-stageable printable paste with low moisture uptake and bleed.	L2 - 260	NA	NA	B-stage + 60 min @ 175°C	NA
6202C™	B-stageable printable paste with low moisture uptake and bleed.	L2 - 260	NA	NA	B-stage + 30 min @ 90°C + 60 min @ 175°C	NA
6204A™	Fast B-stageable printable paste with no die attach cure required. Low outgassing.	L2 - 260	NA	NA	None	NA

### MOLDING COMPOUNDS

PRODUCT	DESCRIPTION	SURFACE FINISH	PACKAGE SIZE	MSL	GREEN	FILLER CONTENT, %	SPIRAL FLOW, cm	CTE <sub>avg</sub> , ppm/°C	Tg, °C
GR828D™	Green, ultra low stress and high adhesion molding compound designed for SOIC, TSOP and QFP packages with lead-free finishing. GR828D™ targets package finishings that require Ag adhesion retention after MSL soaking and IR reflow process.	PPF, Ag	all QFP	L3/260°C	Y	88	100	9	135
GR868™	GR868™ (C102924-129) is a green (non-bromine/antimony and phosphorus) semiconductor grade low stress, low moisture absorption and high adhesion molding compound. It is especially designed for all large and thin packages with highest MSL performance possible on Ni/Pd and Cu/Ag leadframes. It is unique as it offers the highest retention of adhesion even after the harshest reflow condition due to its low modulus at high temperature. It is especially suitable for TQFP and low k packages.	PPF, Ag	all QFP/ LQFP/ TQFP	L2/260°C	Y	87	105	10	110
KLG730™	High adhesion, ultra low stress and green mold compound suitable for SOIC, TSOP, D/D2PAK, QFP, L/TQFP. Its low viscosity properties enables low wire sweep molding with a large operating window. It has no flame retardants but offers 1/8" flammability rating.	PPF, Ag	all QFP	L1/260°C	Y	87	129	7	130

### SOLDER SPHERES

ALLOY	DIAMETER, mm	TOLERANCES ± mm	C <sub>pk</sub>	PACKAGE SIZE		
				SPHERES/BOTTLE	BOTTLE SIZE, CC	SPHERES/BOX
Sn-Ag-Cu Series Sn96.5-Ag3.5 Sn-Ag1-Cu0.5 Sn-Ag2.6-Cu0.6 Sn-Ag3-Cu0.5* Sn-Ag3.8-Cu0.7† Sn-Ag4-Cu0.5†	0.500	0.015	≥1.33	500,000	100	10,000,000
	0.450					
	0.406					
	0.400	40				
	0.350					
	0.304					
Sn-Ag-Cu-Ni-Ge Series Sn-Ag1-Cu0.5-Ni0.05-Ge†† Sn-Ag1.2-Cu0.5-Ni0.02-Ge†† Sn-Ag3-Cu0.5-Ni0.05-Ge††	0.300	0.010	≥1.33	1,000,000	25	20,000,000
	0.250					
	0.200					
	0.180					
CASTIN Series CASTIN125 <sup>en</sup> CASTIN258 <sup>en</sup> CASTIN305 <sup>en</sup>	0.150	0.005	≥1.33	1,000,000	10	20,000,000
	0.100					
	0.080					
Sn-Zn Series Sn91-Zn9 Sn-Zn8-Ag0.5-Ai0.01-Ga0.1	0.050	0.005	≥1.33	1,000,000	10	20,000,000
	0.050					